

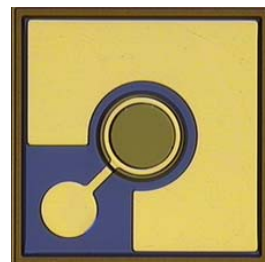
1.25/2.5 Gbps 1310/1550 nm PIN

Part Number: DI2A-7060

Applications: 1.25, 2.5 Gbps (OC-24, OC-48)

Absolute Maximum Ratings (T = 25°C):

Parameter	Symbol	Unit	Value	Note
Forward Current	I _F	mA	10	
Reverse Voltage	V _R	V	20	
Die-Attach Temperature		°C	330	60 Second Max
Operating Temperature	T _{op}	°C	0 to 90	
Storage Temperature	T _{stg}	°C	-40 to +100	



Electro-optical Characteristics (T = 25°C, unless noted otherwise):

Parameter	Symbol	Unit	Min.	Typ.	Max.	Test Condition
Aperture	D	μm	58	60	62	
Responsivity	R	A/W	0.85 0.90	0.90 0.95		λ = 1310 nm λ = 1550 nm
Dark Current	I _D	nA		0.1	1.0	V _R = 2 V
Breakdown Voltage	V _B	V	20			I _R = 1 μA
Capacitance	C	pF		0.7	0.8	V _R = 2 V f = 1 MHz
Rise/Fall Time	τ _r /τ _f	ps		90/90	100/100	V _R = 2 V 20-80%
Cut-off Frequency	f _C	GHz	2.8	3.1		V _R = 2 V R _L = 50 Ω

Chip configuration:

1. Anode contact on top (epi) surface; cathode on substrate back surface.
2. Die size (typical): 300 μm (Wide) x 300 μm (Long) x 160 μm (Thick);
Tolerance: +/- 12.5 μm.
3. Bond pad size: 55 μm round

2.5 Gbps 1310/1550 nm PIN

